1.

Record Nr.	UNISALENTO991003517209707536
Autore	Eco, Umberto
Titolo	Dall'albero al labirinto : studi storici sul segno e l'interpretazione / Umberto Eco
Pubbl/distr/stampa	Milano : Bompiani, 2007
ISBN	9788845259029
Descrizione fisica	575 p. ; 22 cm
Disciplina	121.68 401 149
Soggetti	Filosofia del linguaggio Ermeneutica Semiologia
Lingua di pubblicazione	Italiano
Formato	Materiale a stampa
Livello bibliografico	Monografia
Nota di bibliografia	Contiene riferimenti bibliografici ed indice

2.

Record Nr.	UNINA9910717064403321
Autore	Kiska Wendy
Titolo	Modeling the costs of the Pension Benefit Guaranty Corporation's multiemployer program / / Wendy Kiska, Jason Levine, and Damien Moore
Pubbl/distr/stampa	Washington, D.C. : , : Congressional Budget Office, , 2017
Descrizione fisica	1 online resource (56 pages, 2 unnumbered pages) : color illustrations
Collana	Working paper ; ; 2017-04
Soggetti	Multiemployer pension plans - United States Multiemployer defined benefit pension plans - United States Pensions - Economic aspects - Simulation methods
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Note generali	"June 2017."
Nota di bibliografia	Includes bibliographical references.

3.

Record Nr.	UNINA9910299663303321
Autore	Lee Tae-Kyu
Titolo	Fundamentals of Lead-Free Solder Interconnect Technology : From Microstructures to Reliability / / by Tae-Kyu Lee, Thomas R. Bieler, Choong-Un Kim, Hongtao Ma
Pubbl/distr/stampa	New York, NY : , : Springer US : , : Imprint : Springer, , 2015
ISBN	1-4614-9266-1
Edizione	[1st ed. 2015.]
Descrizione fisica	1 online resource (266 p.)
Disciplina	620 620.11295 620.11297 621.381 621.3815
Soggetti	Electronics Microelectronics Optical materials Electronics - Materials Electronic circuits Electronics and Microelectronics, Instrumentation Optical and Electronic Materials Circuits and Systems
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Note generali	Description based upon print version of record.
Nota di bibliografia	Includes bibliographical references at the end of each chapters and index.
Nota di contenuto	Introduction -- Interconnection : The Joint -- Phase Equilibria and Microstructure of Sn-Ag-Cu Alloys -- Microstructure Development; Solidification and Isothermal Aging -- Thermal Cycling Performance -- Mechanical Stability and Performance -- Chemical and Environment Attack -- Challenges in Future Generation Interconnects: Microstructure Again.
Sommario/riassunto	This unique book provides an up-to-date overview of the fundamental concepts behind lead-free solder and interconnection technology. Readers will find a description of the rapidly increasing presence of

electronic systems in all aspects of modern life as well as the increasing need for predictable reliability in electronic systems. The physical and mechanical properties of lead-free solders are examined in detail, and building on fundamental science, the mechanisms responsible for damage and failure evolution, which affect reliability of lead-free solder joints are identified based on microstructure evolution. The continuing miniaturization of electronic systems will increase the demand on the performance of solder joints, which will require new alloy and processing strategies as well as interconnection design strategies. This book provides a foundation on which improved performance and new design approaches can be based. In summary, this book: Provides an up-to-date overview on lead-free soldering technologies   Covers the fundamentals, implementation, reliability, challenges and risks of lead-free soldering technique Explores emerging technologies in lead-free soldering.